



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

U.S. Serial No. 10/747,603

Applicants: Yoo

Title: Methods for Forming Semiconductor Device Bonding Pads

Filed: December 29, 2003

TC/AU: 2891

Examiner: Chaudhari

Docket No. 20063/OG03-051
(formerly 20063/10018)

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO THE OFFICE ACTION DATED JUNE 27, 2005

Dear Sir:

Please enter the following amendments and consider the following remarks.

The Status of the Claims is reflected in the listing of claims that begins on page 2 of this paper.

Changes to the Drawings begin on page 4 of this paper and include an attached drawing sheet.

Remarks begin on page 5 of this paper.

An **Appendix** including amended drawing figures is attached following the last page of this paper.